

ABSTRACT

SPUTTERING TARGET-BACKING PLATE ASSEMBLY, AND ITS PRODUCTION METHOD

[Abstract] A sputtering target-backing plate assembly obtained by bonding a target material of Mg to a backing plate of Cu-Cr alloy, wherein the target material and the backing plate are bonded via a layer of Ni or an alloy comprising Ni as a main component at the interface therebetween. An object of the present invention is to provide a sputtering target-backing plate assembly that is used when magnesium (Mg) is the sputtering target material, and to resolve problems inherent in magnesium (Mg) and problems related to the selection of a backing plate to be compatible with magnesium by improving the bonding strength between the target and the backing plate in order to improve the sputtering efficiency.

Fig. 1